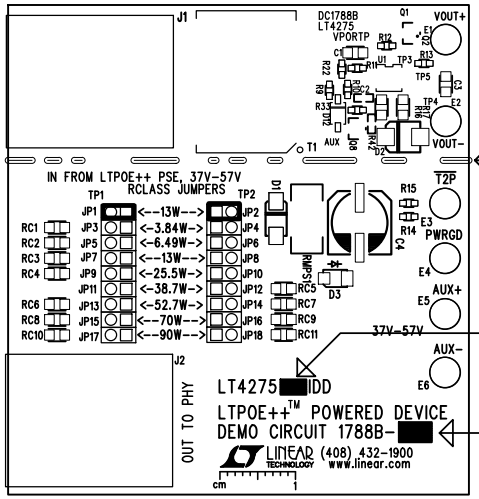
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
–	1	PRODUCTION	KAUNG H.	1-7-2013



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC–A–610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE–OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL D3 AS SHOWN BELOW:

8 MARK EACH LTC PART NUMBER AND ASSEMBLY TYPE WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1
DC1788B–A	LT4275AIDD
DC1788B–B	LT4275BIDD
DC1788B–C	LT4275CIDD

9 DO NOT BREAK THIS SCORE LINE.

APPROVALS	
PCB DES.	KAUNG H.
APP ENG.	KAUNG H.
SCALE = NONE	

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LTC CONFIDENTIAL–
FOR CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING

LTPOE++ POWERED DEVICE

SIZE	IC NO.	REV.
N/A	LT4275XIDD DEMO CIRCUIT 1788B	1

FILENAME: DC1788B–1.PCB | SHT 1 OF 2